

IN THE CLAIMS:

Pursuant to 37 CFR 1.173(b)(2), the entire text of each original claim that is being amended is set forth below with markings showing *changes relative to the patent*. Additionally, the entire text of any newly added claims (relative to the patent) that are being amended herein are underlined in their entirety. An explanation of the changes to the claims is set forth in the remarks section.

A complete listing of claims is attached to this amendment for the convenience of the U.S. Patent and Trademark Office which includes all claims with markings to show changes in the claims *relative to the patent*.

Please amend claims 1, 13, 16 and 19 as set forth below.

1. (Currently Amended) An integrated circuit testing apparatus for testing an integrated circuit leaving an IC singulation station, comprising:
 - a) a receiving means positioned in a pre test position for receiving the integrated circuit from the IC singulation station;
 - b) a testing site, positioned to secure the integrated circuit after a displacement of said receiving means to a test position, the displacement positioning said integrated circuit in said testing site said [test] testing site having a test connection for making physical contact with said integrated circuit when it is secured in said testing site, a circuit test performed on said integrated circuit when it is secured in said testing site; and
 - c) a holding station having a first post test position and a second post test position, said holding station receiving the integrated circuit in said first post test position from the receiving means following a return of the receiving means to said pre test position subsequent to the performing of the circuit test of the integrated circuit;
 - d) a first track for receiving the integrated circuit from the holding station when the holding station is in said first post test position and when the circuit test

- determines that the integrated circuit has a first test condition: and
- e) a second track for receiving the integrated circuit from the holding station when the holding station is in said second post test position, said second test position attained when said receiving means returns to said test position, said second track receiving the integrated circuit when the circuit test determines that the integrated circuit has a second test condition.

13. (Currently Amended) A method of testing an integrated circuit in a testing apparatus having a test site, a holding station, a non-defective integrated circuit track, a defective integrated circuit track, a first position, and a second position, after singulation of the integrated circuit in an integrated circuit singulation apparatus, the method comprising:
transferring the integrated circuit from the integrated circuit singulation apparatus;
receiving the integrated circuit at the testing apparatus while the testing apparatus is in the first position;
moving the testing apparatus to the second position;
testing the integrated circuit to identify defective and non-defective conditions of the integrated circuit;
moving the testing apparatus to the first position to allow the tested integrated circuit to proceed to the holding station in a first unloading position while receiving a second singulated integrated circuit into the testing apparatus;
allowing non-defective integrated circuits to proceed to the non-defective integrated circuit track from the first unloading position; and
moving the holding station to a second unloading position and allowing defective integrated circuits to proceed to the defective integrated circuit track.

16. (Currently Amended) A method of testing an integrated circuit after singulation thereof using a testing apparatus having a test site, a holding station, a non-defective integrated

circuit track, a defective integrated circuit track, a first position, and a second position, the method comprising:
transferring the integrated circuit from an integrated circuit singulation apparatus;
receiving the integrated circuit at the testing apparatus while the testing apparatus is in the first position;
moving the testing apparatus to the second position;
testing the integrated circuit thereby identifying defective and non-defective conditions thereof;
moving the testing apparatus to the first position after testing of the integrated circuit;
allowing the tested integrated circuit to proceed to the holding station in a first unloading position;
receiving a second singulated integrated circuit into the testing apparatus while in the first position;
unloading non-defective integrated circuits to the non-defective integrated circuit track from the first unloading position; and
moving the holding station to a second unloading position and unloading defective integrated circuits to the defective integrated circuit track.

19. (Currently Amended) A method of testing an integrated circuit in a testing apparatus having a test site, a holding station, a non-defective integrated circuit track, a defective integrated circuit track, a first position, and a second position, after singulation of the integrated circuit in an integrated circuit singulation apparatus, the method comprising:
receiving the integrated circuit at the testing apparatus while the testing apparatus is in the first position;
moving the testing apparatus to the second position;
testing the integrated circuit to identify defective and non-defective conditions of the integrated circuit;

moving the testing apparatus to the first position to allow the tested integrated circuit to proceed to the holding station in a first unloading position while receiving a second singulated integrated circuit into the testing apparatus;
allowing non-defective integrated circuits to proceed to the non-defective integrated circuit track from the first unloading position; and
moving the holding station to a second unloading position and allowing defective integrated circuits to proceed to the defective integrated circuit track.